

1. Release Notes

1.1 Product Release Information

Table 1. Product Identification

Parameter	Description
Library Name	C28SOI_IO_ALLF_IOSUPPLYKIT_EG_6U1X2T8XLB
Library Version	7.1
Library Type	IO Cells
Technology	CMOS028_FDSOI
DK Version	

1.2 Impact of Product Release

For latest information, please refer to LYS (<http://col2.cro.st.com/libyield>).

1.3 Related Documentation

- C28SOI_IO_ALLF_IOSUPPLYKIT_EG_7.1 Release Notes and Known Problems and Solutions
- C28SOI_IO_ALLF_IOSUPPLYKIT_EG User Manual

2. Changes with respect to all Previous Versions

2.1 Changes in Version 7.1 w.r.t Version 7.0

Final release aligned with latest BE

Impacted cells : IOSUPPLYKIT_TOP_ESD_IP_RING_REMOTE_3V3_CLAMP_BIAS_*

2.2 Version 7.0

A. This is the Final release.

B. This package contains SIGNOFF GDS, CDL and SYNOPSYS LAYOUT.

3. Known Problems and Solutions of this release



This document is compatible for viewing with acroread 7.0 and later versions. If opened with a lower version of acroread, there might be some color display problem.



———— DRC errors ————

EMET errors:

EMET.DEN.1 - - Corrected at chip level

EMET.DEN.2 - -

EMET.DEN.3 - -

EMET.DEN.4 - -

EMET.DEN.5 - -

EMET.DEN.6 - -

EMET.DEN.7 - -

EMET.DEN.8 - -

EMET.DEN.9 - -

EMET.DEN.10 - -

EMET.DEN.11 - -

EMET.DEN.12 - -

DENSITY errors:

RX.DEN.1

PC.DEN.1

M1.DEN.1 - - Min density, corrected by tiles

M2.DEN.1 - -

M3.DEN.1 - -

M5.DEN.1 - -

M6.DEN.1 - -

IA.DEN.1 - -

IB.DEN.1 - -

PC.DEN.8 - IOSUPPLYKIT_EX_TOP_ESD_IP_IORING_B2B_DIODE_STI_40UM and IOSUPPLYKIT_EX_TOP_ESD_IP_IORING_REMOTE_1V0/1V8_SCR_WITH_B2B - Min density, corrected by tiles

M2.DEN.8 - "IOSUPPLYKIT_EX_TOP_ESD_IP_IORING_IO_ANA_UHF and IOSUPPLYKIT_EX_TOP_ESD_IP_IORING_B2B_DIODE_STI_29UM" -

M3.DEN.8 - -

M5.DEN.8 -

M6.DEN.8 - -

IA.DEN.8 - -

IB.DEN.8 - -

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———— LVS/ERC errors on Topcells ————

**ERC1a - IOSUPPLYKIT_EX_TOP_ESD_IP_CORECELL_B2B_NFING6/_NFING8 - Cor-
rected at chip level**

**SOFTCHECK error: stamping conflict - IOSUPPLYKIT_EX_TOP_ESD_IP_CORECELL -
B2B_NFING8 - Corrected by using SXCUT drawing**



———— LVS errors on allcells ————

ERC1a - All allcells - Corrected at chip level

4. Contact Information

For more information about this product/IP/Library or any problems or suggestions, please contact **HELPDESK** (<http://col2.cro.st.com/helpdesk>).

Non-ST users, please contact the respective Customer Support.



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